

Electronic Patent Application Fee Transmittal

Application Number:	10633839			
Filing Date:	04-Aug-2003			
Title of Invention:	SYSTEM FOR, AND METHOD OF, ETCHING A SURFACE ON A WAFER			
First Named Inventor/Applicant Name:	Pavel N. Laptev			
Filer:	Sheldon R. Meyer/Patricia Diehl			
Attorney Docket Number:	TEGL-01212US1			
Filed as Small Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	2501	1	700	700
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1000